

Q1  
an outside frame formed with positioning holes,  
said tie bar being connected to said outside frame; and

a deformable portion included in said tie bar for  
preventing said outside frame from deforming under  
extraneous physical stress.--

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Q2  
--5. (amended) A frame comprising a combination  
of lead frames arranged such that element loading portions  
to be loaded with semiconductor elements thereof are  
positioned one above the other, said lead frames each  
comprising:

a tie bar to which the element loading portions  
are connected by lead forming portions;

an outside frame formed with positioning holes,  
said tie bar being connected to said outside frame; and

a deformable portion included in said tie bar for  
preventing said outside frame from deforming under physical  
stress.--

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Q3  
--12. (amended) The semiconductor device as  
claimed in claim 11, wherein the leads are positioned on an  
extension of a bottom of said seal resin so that a bottom  
surface of said leads and a bottom surface of said seal  
resin are coplanar.--

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